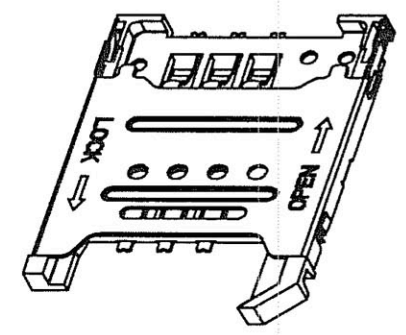
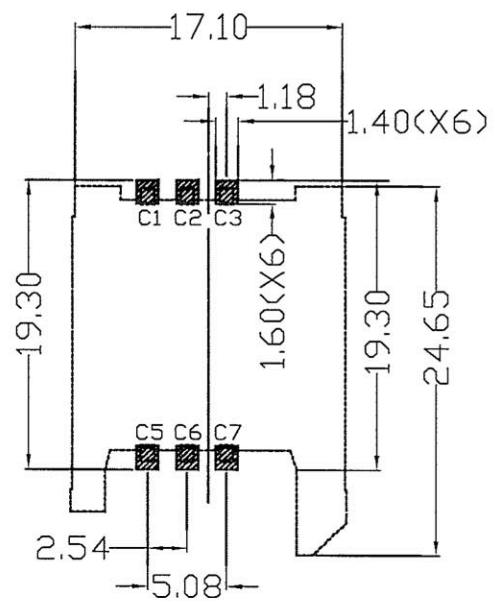
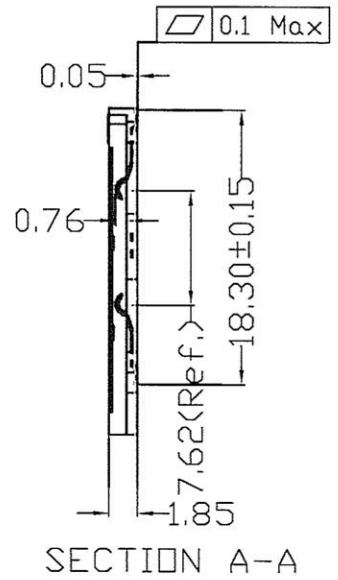
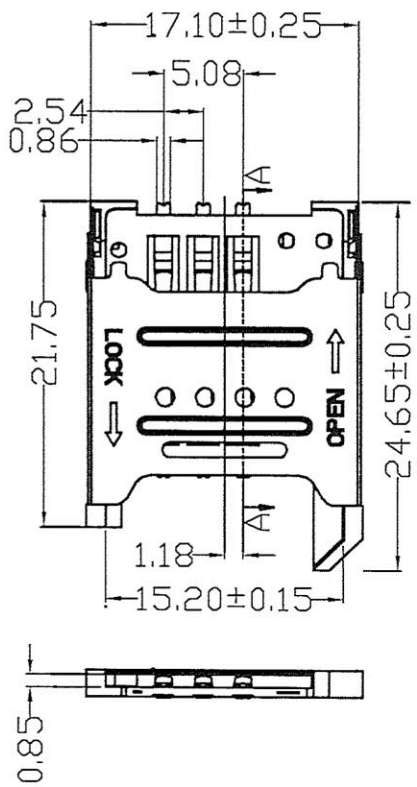


1 2 3 4 5 6 7 8

A
B
C
D
E
F
G
H



REFRENC PCB LAYOUT
GENERAL TOLERANCE ±0.05

TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 24.60Lx17.70Wx1.80±0.10H mm
Weight: Approx0.6±0.2g
Contact principle:Friction technology
Operating position:shaft up/down/horizontal
Mounting System:SMT(without post)
Durability:5000 cycles min.

2.Mechanical characteristics:

Insulation material:Thermoplastic,UL 94V-0

3.Electrical Characteristics

Number of contacts : 6pins
contact resistance: 50mΩtypical,100mΩmax
insulation resistance:>1000MΩ/500V DC

4.Solderability

wave:Not applicable
Vaporphase: 215°C, 30sec. Max
IR reflow: 230°C,15sec.Max
Manual soldering : 360°C,3sec.Max

5.Environmental Characteristics

Operating temperature: -40°C~+85°C
Operating humidity :10%~+95%RH
Storage temperature: -40°C~+85°C
Storage Humidity:10%~95%RH
thermal shock: -40°C~+85°C,5cycles
Damp Heat: 40°C,90%RH,10days.
Salt-Mist: 35°C,5%NaCl,24HR

RoHS
Compliant

HSM 玄茂科技股份有限公司
HSUAN MAO TECHNOLOGY CO., LTD.

APPD. 核准
DWG. 製圖
DATE 制表日
2013/12/26

SCALE 比例 參考
UNIT 單位 MM
PAGE 張數 1 OF 1

TOLERANCE 容許公差
0 ± 0.25
.00 ± 0.15
ANG. ±
SIZE. 紙張尺寸 A4
REV. 版本 A
PART NAME 品名
SIM CARD HINGED TYPE 6P
INSULATOR HEIGHT:1.85mm
SELECTIVE GOLD PALTING
BLACK COLOR REEL PACKING ROHS
PART NO.
料號 C0635-06DASBR0R

A
B
C
D
E
F
G
H

1 2 3 4 5 6 7 8